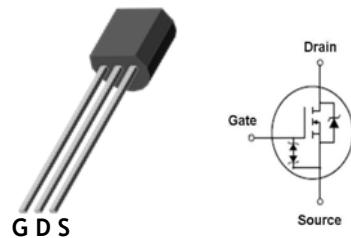


SWITCHING REGULATOR APPLICATION

Features

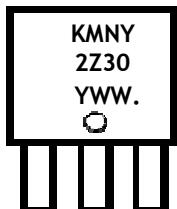
- High voltage: $BV_{DSS}=300V$ (Min.)
- Low gate charge: $Q_g=2.9nC$ (Typ.)
- Low drain-source On resistance: $R_{DS(on)}=8\Omega$ (Max.)
- Built-in protection zener diode
- RoHS compliant device



Ordering Information

Part Number	Marking	Package
KCKMNY2Z30	KMNY 2Z30 YWW.	TO-92

Marking Information



Column 1, 2: Device Code
 Column 3: Production Information
 e.g.) YWW
 -.. YWW: Date Code (year, week)
 -.. : Dalian

Absolute maximum ratings ($T_a=25^\circ C$ unless otherwise noted)

Characteristic	Symbol		Rating	Unit
Drain-source voltage	V_{DSS}		300	V
Gate-source voltage	V_{GSS}		± 30	V
Drain current (DC) *	I_D	$T_a=25^\circ C$	0.2	A
		$T_a=100^\circ C$	0.12	A
Drain current (Pulsed) *	I_{DM}		1	A
Avalanche current ^(Note 2)	I_{AS}		1.3	A
Single pulsed avalanche energy ^(Note 2)	E_{AS}		182.6	mJ
Repetitive avalanche current ^(Note 1)	I_{AR}		0.2	A
Repetitive avalanche energy ^(Note 1)	E_{AR}		1.5	mJ
Power dissipation	P_D		0.6	W
Junction temperature	T_J		150	°C
Storage temperature range	T_{stg}		-55~150	°C

* Limited only maximum junction temperature

Thermal Characteristics

Characteristic	Symbol	Rating	Unit
Thermal resistance, junction to ambient	$R_{th(j-a)}$	Max. 200	°C/W

Electrical Characteristics ($T_a=25^\circ C$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV_{DSS}	$I_D=250\mu A, V_{GS}=0$	300	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu A, V_{DS}=V_{GS}$	1.5	2	2.5	V
Drain-source cut-off current	I_{DSS}	$V_{DS}=300V, V_{GS}=0V$	-	-	1	uA
Gate leakage current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 10V$	-	-	± 10	uA
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=100mA$	-	6	8	Ω
Forward transfer conductance ^(Note 3)	g_{fs}	$V_{DS}=10V, I_D=100mA$	-	0.4	-	S
Input capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$	-	101	130	pF
Output capacitance	C_{oss}		-	15	20	
Reverse transfer capacitance	C_{rss}		-	3.2	5	
Turn-on delay time ^(Note 3,4)	$t_{d(on)}$	$V_{DD}=150V, I_D=0.2A$ $R_G=25\Omega$	-	5	-	ns
Rise time ^(Note 3,4)	t_r		-	17	-	
Turn-off delay time ^(Note 3,4)	$t_{d(off)}$		-	21	-	
Fall time ^(Note 3,4)	t_f		-	35	-	
Total gate charge ^(Note 3,4)	Q_g	$V_{DS}=240V, V_{GS}=10V$ $I_D=0.2A$	-	2.9	4.5	nC
Gate-source charge ^(Note 3,4)	Q_{gs}		-	0.4	-	
Gate-drain charge ^(Note 3,4)	Q_{gd}		-	0.7	-	

Source-Drain Diode Ratings and Characteristics ($T_a=25^\circ C$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current (DC)	I_S	Integral reverse diode in the MOSFET	-	-	0.2	A
Source current (Pulsed)	I_{SM}		-	-	1	A
Forward voltage	V_{SD}	$V_{GS}=0V, I_S=8A$	-	-	1.4	V
Reverse recovery time ^(Note 3,4)	t_{rr}	$I_S=0.2A, V_{GS}=0V$ $dI_F/dt=100A/us$	-	270	-	ns
Reverse recovery charge ^(Note 3,4)	Q_{rr}		-	0.27	-	uC

Gate to Source Zener Diode Characteristic ($T_a=25^\circ C$ unless otherwise noted)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Gate-Source breakdown voltage	$IG=\pm 1mA, V_{DS}=0V$	± 20	± 24	-	V

Note:

1. Repeated rating: Pulse width limited by safe operating area
2. $L=8.9mH, I_{AS}=8A, V_{DD}=50V, R_G=25\Omega$, Starting $T_J=25^\circ C$
3. Pulse test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$
4. Essentially independent of operating temperature typical characteristics

Electrical Characteristic Curves

Fig. 1 $I_D - V_{DS}$

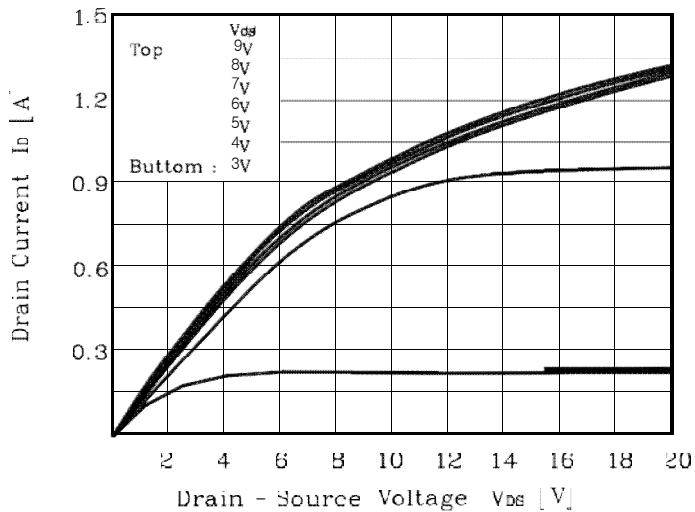


Fig. 2 $I_D - V_{GS}$

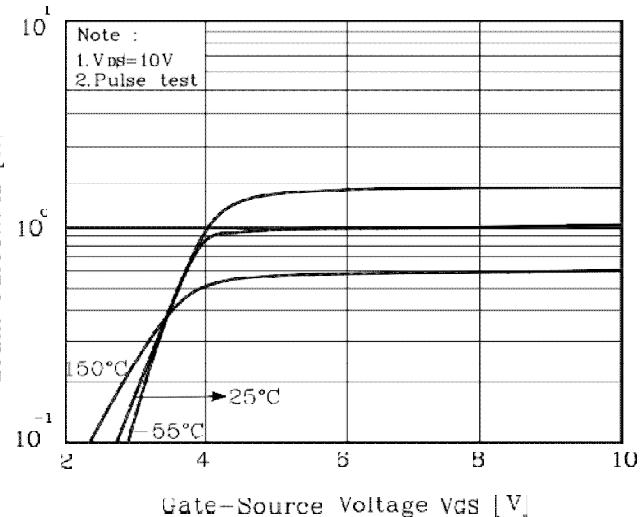


Fig. 3 $R_{DS(ON)} - I_D$

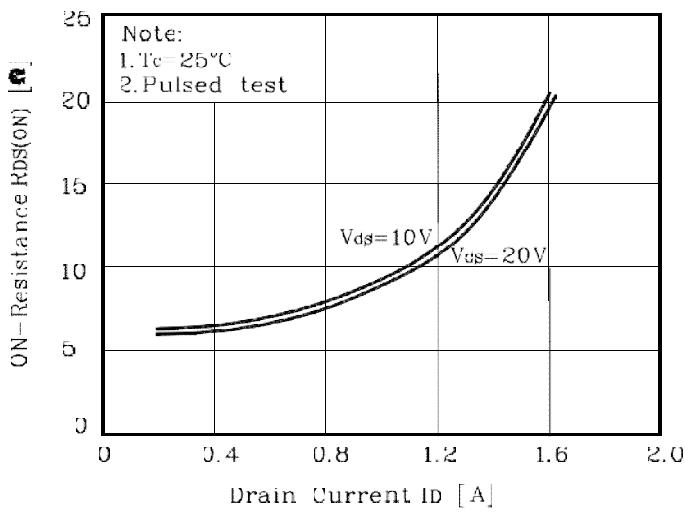


Fig. 4 $I_S - V_{SD}$

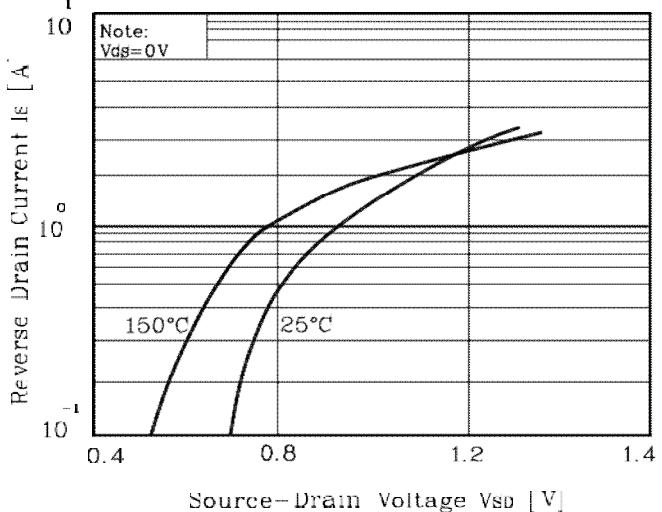


Fig. 5 Capacitance - V_{DS}

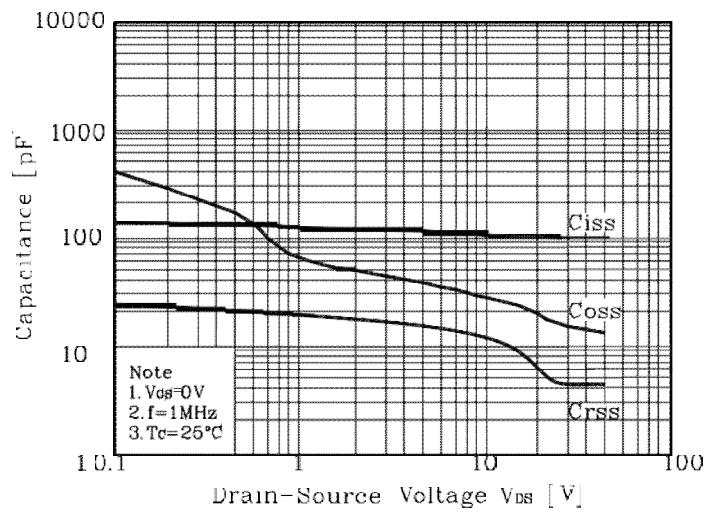
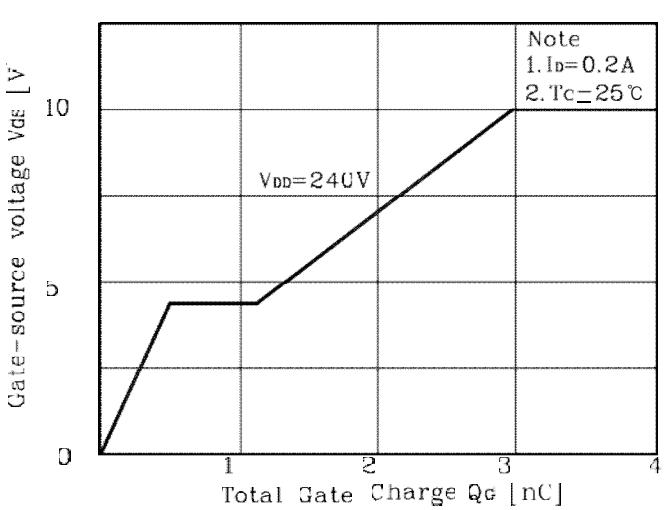


Fig. 6 $V_{GS} - Q_G$



Electrical Characteristic Curves (Continue)

Fig. 7 BV_{DSS} - T_J

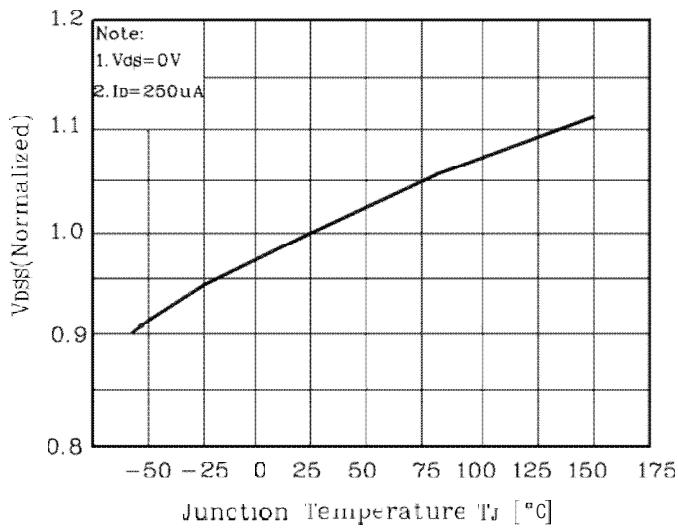


Fig. 8 R_{DSON} - T_J

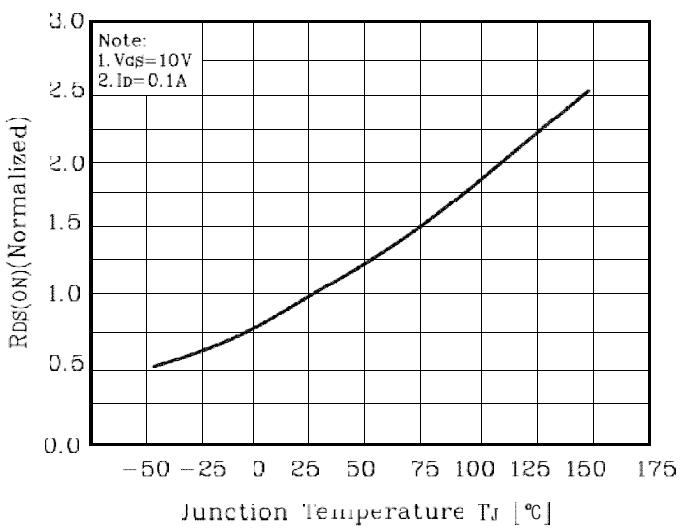


Fig. 9 I_D - T_C

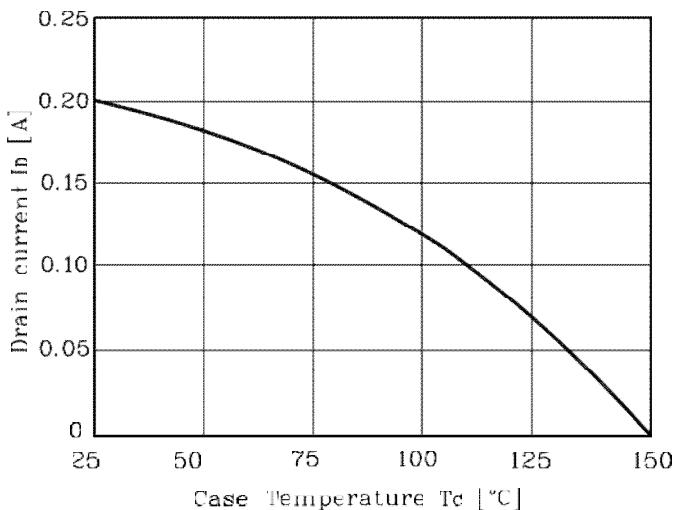


Fig. 10 Safe Operating Area

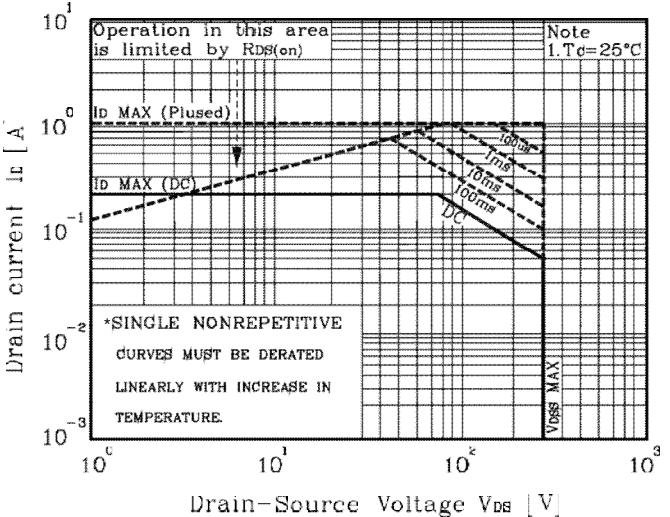


Fig. 11 Gate Charge Test Circuit & Waveform

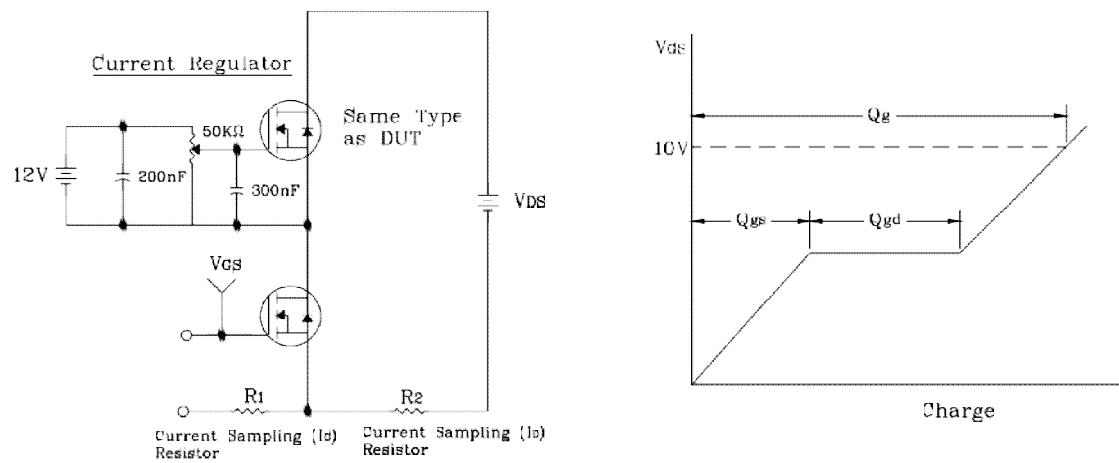


Fig. 12 Resistive Switching Test Circuit & Waveform

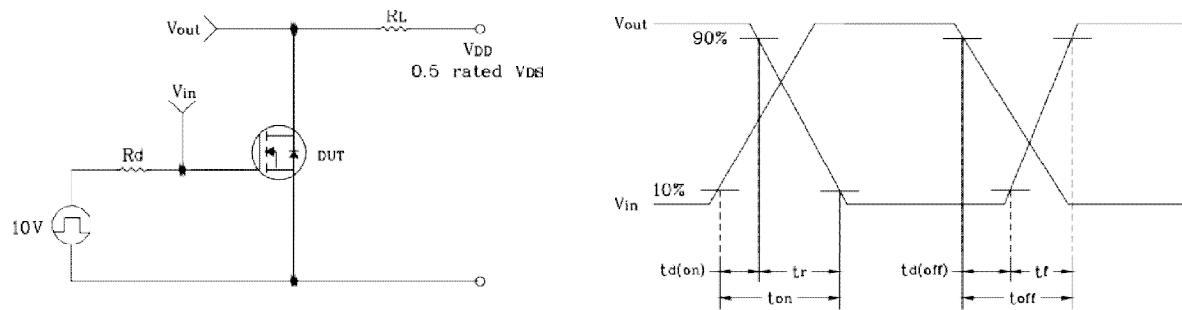


Fig. 13 E_{AS} Test Circuit & Waveform

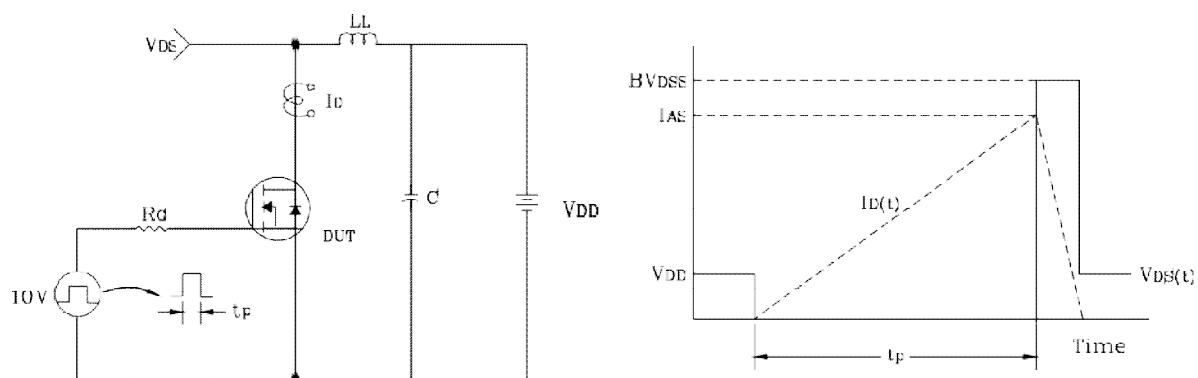
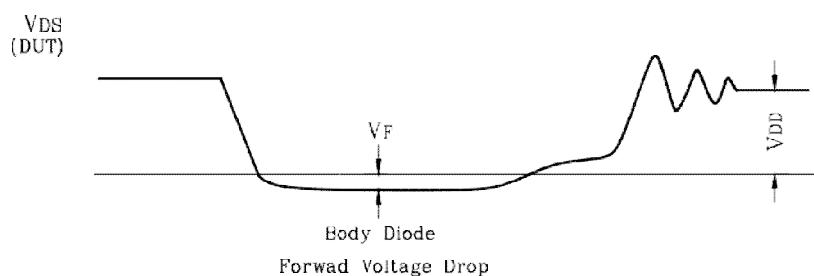
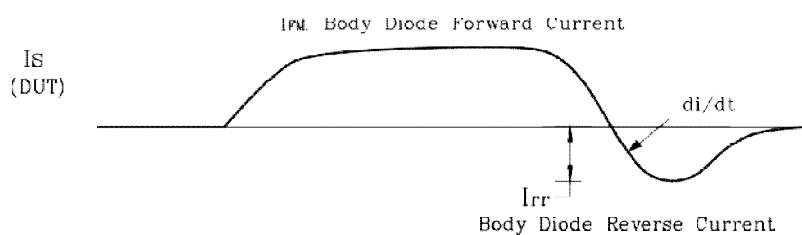
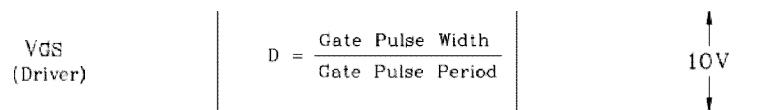
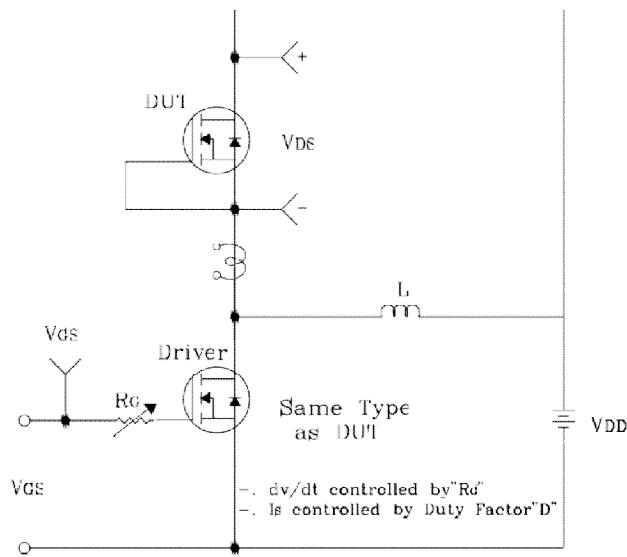
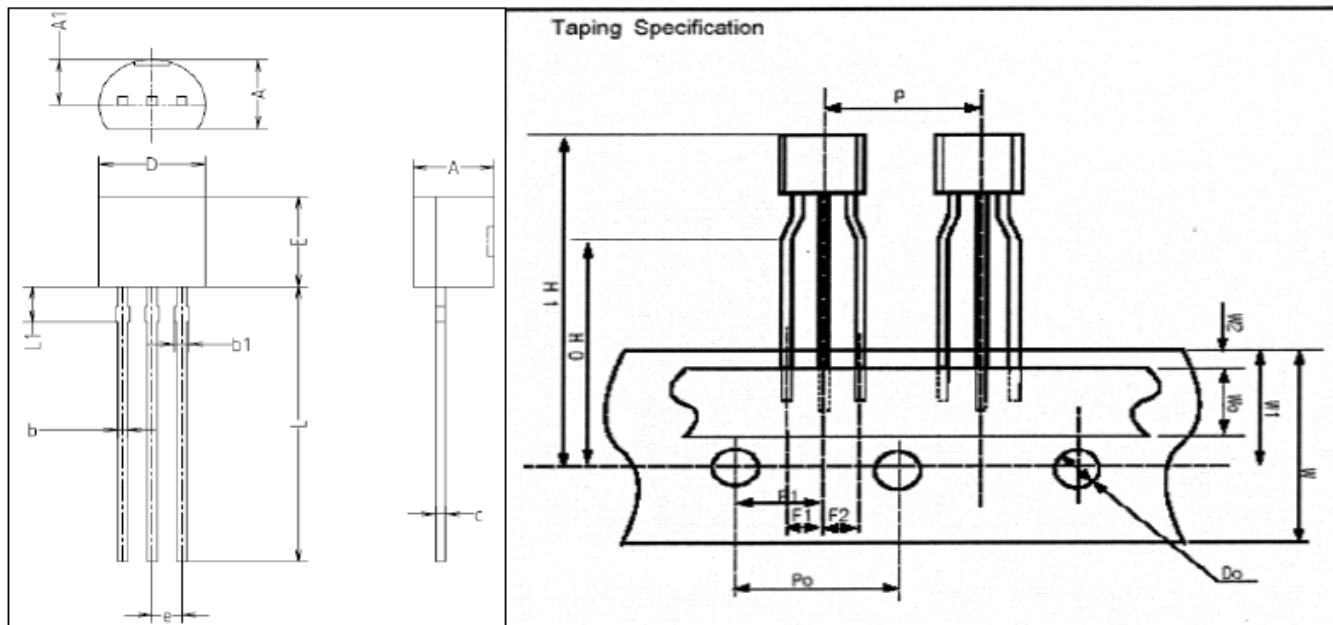


Fig. 14 Diode Reverse Recovery Time Test Circuit & Waveform



Package Outline Dimensions



Package Dimension(Unit : mm)				Taping Dimension(Unit : mm)			
Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	3.40	3.56	3.66	P	12.2	12.7	13.2
A1	2.46	2.54	2.59	P0	12.5	12.7	12.9
b	0.39	0.48	0.53	P1	5.85	6.35	6.85
b1	0.39	-	0.63	F1,F2	2.4	2.5	2.9
c	0.35	0.42	0.47	W	17.5	18.0	19.0
D	4.48	4.60	4.70	W0	5.5	6.0	6.5
E	4.48	4.60	4.70	W1	8.5	9.0	9.5
e	1.17	1.27	1.37	W2	-	-	1.0
L	13.70	14.47	14.77	H0	15.5	16.0	16.5
L1	1.55	1.70	2.15	H1	-	-	27.0
				D0	3.8	4.0	4.2

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